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ICS 77.150.30
CCS H 62

YS

NONFERROUS METALS INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

YS/T 678-2024

Replacing YS/T 678-2008

Bonding copper wire for semiconductor packaging

(English Translation)

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What this standard covers

This standard specifies the classification and marking, technical requirements, test methods, inspection rules, marking, packaging, transportation, storage, accompanying documents and order forms of bonding copper wire for semiconductor packaging. This standard applies to bonding copper wire for semiconductor packaging.

Document data

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